

Title (en)

Method for surface treatment of aluminum or aluminum alloy

Title (de)

Verfahren zur Oberflächenbehandlung von Aluminium und Aluminiumlegierung

Title (fr)

Methode pour le traitement de surface d'aluminium et d'alliage d'aluminium

Publication

EP 1207220 A1 20020522 (EN)

Application

EP 01125530 A 20011025

Priority

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Abstract (en)

This method employs the electrolyte which consists mainly of a sulfuric acid bath, an oxalic acid bath, or their mixture bath added with either a metal nitrate selected from silver nitrate, copper nitrate, and their combination or a metal sulfate selected from silver sulfate, copper sulfate, and their combination and allows the base material immersed in the electrolyte to be fed with an AC/DC combined current, a negative PR waveform current, or a negative pulse waveform current so as to develop an anodized layer on the surface of the base material and simultaneously deposit in the anodized layer a metal separated from either the metal nitrate or the metal sulfate. Accordingly, both the development of the anodized layer and the deposition of metal can be implemented by a single action of the electrolytic process. <IMAGE>

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IPC 8 full level

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Citation (search report)

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